

**60A 650V Trench Fieldstop IGBT with anti-parallel diode SRE60N065FSU2DG**
**General Description**

The SRE60N065FSU2DG is a Field Stop Trench IGBT with anti-parallel diode, which offers ultra-low switching losses, high energy efficiency for switching applications such as PFC, Power Supply, Inverter, etc.

The SRE60N065FSU2DG package is TO-247.

**Features**

- High Breakdown Voltage to 650V
- Advanced Trench Fieldstop technology
  - Smooth Switching Off with Lower Spike
  - High Ruggedness, Temperature Stability
  - Easy Parallel Switching Capability due to Positive Temperature Coefficient in  $V_{CE(SAT)}$
- LOW  $V_{CE(SAT)}$
- Enhanced Avalanche Capability
- Non-Automotive Qualified

**Application**

- Inverter
- Uninterruptible power supplies
- PFC application
- Converter with high switching frequency

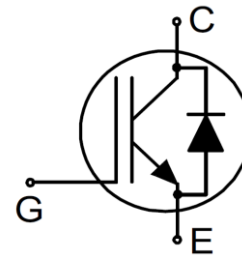
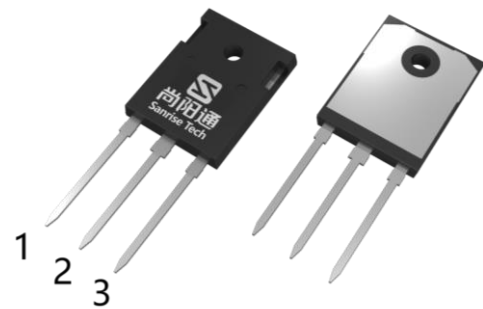
**Symbol**


Figure 1 Symbol of SRE60N065FSU2DG

**Package Type**


TO-247

- Pin 1- gate
- Pin 2&backside-collector
- Pin 3-emitter

Figure 2 Package Type of SRE60N065FSU2DG

**Ordering Information**

SRE60N065FSU2DG □ □ - □

Circuit Type			G: Green
Package			Blank: Tube
T: TO-247			TR: Tape & Reel

Package	Part Number	Marking ID	Packing Type
TO-247	SRE60N065FSU2DGT-G1	SRE60N065FSU2DGTG1	Tube

**60A 650V Trench Fieldstop IGBT with anti-parallel diode SRE60N065FSU2DG**
**Absolute Maximum Ratings**

Parameter		Symbol	Rating	Unit
Collector-emitter Voltage		$V_{CES}$	650	V
Gate-emitter Voltage		$V_{GES}$	$\pm 20$	V
Transient Gate-emitter Voltage			$\pm 30$	V
Continuous Collector Current	$T_C=25^\circ\text{C}$	$I_C$	120	A
	$T_C=100^\circ\text{C}$		60	
Pulsed Collector Current, Limited by $T_{Jmax}$		$I_{CM}$	240	A
Diode Continuous Collector Current	$T_C=25^\circ\text{C}$	$I_F$	70	A
	$T_C=100^\circ\text{C}$		$40^{(1)}$	
Diode Pulsed Current, Limited by $T_{Jmax}$		$I_{FM}$	120	A
Power Dissipation	$T_C=25^\circ\text{C}$	$P_{tot}$	306	W
	$T_C=100^\circ\text{C}$		153	
Operating Junction Temperature Range		$T_J$	$-40 \sim 175^{(2)}$	$^\circ\text{C}$
Storage Temperature Range		$T_{STG}$	$-55 \sim 150$	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		$T_{LEAD}$	260	$^\circ\text{C}$

Note:

1. Current level is limited by  $T_{j\_max}$ .
2. Reliability testing conducted at  $T_{Jmax}=175^\circ\text{C}$ .

**Thermal Resistance**

Parameter	Symbol	Min.	Typ.	Max.	Unit
IGBT Thermal Resistance, Junction-to-Case	$R_{thJC}$	-	-	0.49	$^\circ\text{C/W}$
Diode Thermal Resistance, Junction-to-Case	$R_{thJC}$	-	-	1.0	
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	-	-	40	

**60A 650V Trench Fieldstop IGBT with anti-parallel diode SRE60N065FSU2DG**
**Electrical Characteristics**
 $T_J = 25^\circ\text{C}$ , unless otherwise specified.

Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Statistic Characteristics</b>								
Collector-emitter Voltage	Breakdown	$BV_{CES}$	$V_{GE}=0V, I_C=250\mu A$	650			V	
Gate Threshold Voltage		$V_{GE(th)}$	$V_{CE}=V_{GE}, I_C=250\mu A$	4.2	4.8	5.4	V	
Collector-emitter saturation voltage		$V_{CEsat}$	$V_{GE}=15V, I_C=60A,$ $T_J=25^\circ\text{C}$	1.45	1.51	1.68	V	
			$T_J=125^\circ\text{C}$		1.81		V	
			$T_J=175^\circ\text{C}$		2.02		V	
Zero Gate Voltage Collector Current		$I_{CES}$	$V_{CE}=650V, V_{GE}=0V$ $T_J=25^\circ\text{C}$		0.1	40	$\mu A$	
			$T_J=175^\circ\text{C}$			1	mA	
Gate-emitter Current	Leakage Forward	$I_{GESF}$	$V_{GE}=20V, V_{CE}=0V$			100	nA	
	Reverse	$I_{GESR}$	$V_{GE}=-20V, V_{CE}=0V$			-100	nA	
<b>Dynamic Characteristics</b>								
Input Capacitance		$C_{IES}$	$V_{CE}=25V, V_{GE}=0V,$ $f=100\text{KHz}$		2460		pF	
Output Capacitance		$C_{OES}$			247			
Reverse Transfer Capacitance		$C_{RES}$			48			
Gate Resistance		$R_G$	$f=1\text{ MHz, Open Drain}$		1.7		$\Omega$	
Turn-on Delay Time		$t_{d(on)}$	$T_J=25^\circ\text{C}$ $V_{CC}=400V, I_C=60A$ $R_G=10\Omega, V_{GE}=0/15V$ Energy losses include "tail" and diode reverse recovery		21		ns	
Rise Time		$t_r$			38		ns	
Turn-off Delay Time		$t_{d(off)}$			122		ns	
Fall Time		$t_f$			70		ns	
Turn-on energy		$E_{on}$			1.34		mJ	
Turn-off energy		$E_{off}$			0.63		mJ	
Total switching energy		$E_{ts}$			1.97		mJ	
Turn-on Delay Time		$t_{d(on)}$		$T_J=150^\circ\text{C}$ $V_{CC}=400V, I_C=60A$ $R_G=10\Omega, V_{GE}=0/15V$ Energy losses include "tail" and diode reverse recovery		18		ns
Rise Time		$t_r$				39		ns
Turn-off Delay Time		$t_{d(off)}$				149		ns
Fall Time		$t_f$			118		ns	
Turn-on energy		$E_{on}$			2.43		mJ	
Turn-off energy		$E_{off}$			0.92		mJ	
Total switching energy		$E_{ts}$			3.35		mJ	
Gate to Emitter Charge		$Q_{GE}$	$V_{CC}=400V, I_C=60A$ $V_{GE}=0\text{ to }15V$		28		nC	
Gate to Collector Charge		$Q_{GC}$			91			
Gate Charge Total		$Q_G$			190			

**60A 650V Trench Fieldstop IGBT with anti-parallel diode SRE60N065FSU2DG**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Reverse Diode Characteristics</b>						
Diode Forward Voltage	$V_F$	$I_F=30A$ $T_J=25^\circ C$		1.61	1.89	V
		$I_F=30A$ $T_J=125^\circ C$		1.44		
		$I_F=30A$ $T_J=175^\circ C$		1.34		
		$I_F=60A$ $T_J=25^\circ C$		1.89	2.22	V
		$I_F=60A$ $T_J=125^\circ C$		1.79		
		$I_F=60A$ $T_J=175^\circ C$		1.68		
Reverse Recovery Time	$t_{rr}$	$T_J=25^\circ C$ $V_R=400V, I_F=30A$ $dI_F/dt=1100A/us$		130		ns
Reverse Recovery Charge	$Q_{rr}$			0.72		uC
Peak Reverse Recovery Current	$I_{rrm}$			18		A
Diode peak rate of fall of reverse Recovery current during tb	$dI_{rr}/dt$			-456		A/us
Reverse Recovery Time	$t_{rr}$	$T_J=25^\circ C$ $V_R=400V, I_F=60A$ $dI_F/dt=1000A/us$		179		ns
Reverse Recovery Charge	$Q_{rr}$			0.84		uC
Peak Reverse Recovery Current	$I_{rrm}$			19		A
Diode peak rate of fall of reverse Recovery current during tb	$dI_{rr}/dt$			-375		A/us
Reverse Recovery Time	$t_{rr}$	$T_J=150^\circ C$ $V_R=400V, I_F=30A$ $dI_F/dt=1100A/us$		143		ns
Reverse Recovery Charge	$Q_{rr}$			1.34		nC
Peak Reverse Recovery Current	$I_{rrm}$			25		A
Diode peak rate of fall of reverse Recovery current during tb	$dI_{rr}/dt$			-523		A/us
Reverse Recovery Time	$t_{rr}$	$T_J=150^\circ C$ $V_R=400V, I_F=60A$ $dI_F/dt=1000A/us$		223		ns
Reverse Recovery Charge	$Q_{rr}$			1.93		uC
Peak Reverse Recovery Current	$I_{rrm}$			26		A
Diode peak rate of fall of reverse Recovery current during tb	$dI_{rr}/dt$			-394		A/us



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